



- NOTES: 1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
 2. DIE ATTACH AREA TO BE METALLIZED
 3. SEAL AREA TO BE METALLIZED
 4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
 5. LEAD RESISTANCE: 0.15 Ω MAX.

FW014W750-1 S=0 D=0

CHANGE DATE DRAWN CHECKED APPROVED	NAME 14 LEAD FLAT PACKAGE		TOLERANCES: UNLESS OTHERWISE SPECIFIED ±.005	DRAWN <i>S. J. J.</i>	CHECKED <i>T. A.</i>
	SCALE 8 : 1	MATERIAL AS INDICATED		APPROVED	DATE SEP. 27 '89
	KYOCERA CORPORATION KYOTO JAPAN			DWG. NO. KD-F89750	